

Ultrason® S 2010 G4

Polysulfone (PSU)

Product Description

Ultrason S 2010 G4 is a 20% glass reinforced, medium viscosity injection molding PSU grade with high rigidity and strength.

Applications

Typical applications include circuit breaker parts, lamp holders, heat shields, impellers, and printer cartridges.

PHYSICAL	ISO Test Method	Property Value
Density, g/cm	1183	1.38
Mold Shrinkage, parallel, %	294-4	0.31
Mold Shrinkage, normal, %	294-4	0.52
Moisture, %	62	
(50% RH)		0.2
(Saturation)		0.7
RHEOLOGICAL	ISO Test Method	Property Value
Melt Volume Rate (360 C/10 Kg), cc/10min.	1133	40
MECHANICAL	ISO Test Method	Property Value
Tensile Modulus, MPa	527	
23C		6,800
Tensile stress at break, MPa	527	
23C		110
Tensile strain at break, %	527	
23C		2.2
Tensile Creep Modulus (1000h), MPa	899	6,000
IMPACT	ISO Test Method	Property Value
Izod Notched Impact, kJ/m ²	180	
23C		7
Charpy Notched, kJ/m ²	179	
23C		7
-30C		7
Charpy Unnotched, kJ/m ²	179	
23C		45
-30C		45
THERMAL	ISO Test Method	Property Value
HDT A, C	75	183
Coef. of Linear Thermal Expansion, Parallel, mm/mm C		0.26 X10 ⁻⁴
ELECTRICAL	ISO Test Method	Property Value
Comparative Tracking Index	IEC 60112	125
Volume Resistivity	IEC 60093	>1E13
Surface Resistivity	IEC 60093	>1E14
Dielectric Constant (100 Hz)	IEC 60250	3.5



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Dielectric Constant (1 MHz)	IEC 60250	3.5
Dissipation Factor (100 Hz)	IEC 60250	10
Dissipation Factor (1 MHz)	IEC 60250	60
Dielectric Strength, KV/mm	IEC 60243-1	46
UL RATINGS	UL Test Method	Property Value
Flammability Rating, 1.5mm	UL94	V-1
Relative Temperature Index, 1.5mm	UL746B	
Mechanical w/o Impact, C		160
Mechanical w/ Impact, C		140
Electrical, C		160

